

# 3EC-M2S-VLP

- ・ 極低粗糙度銅箔，適用於細線路蝕刻之減成法製程。  
Low profile copper foil, suitable for fine etching in the subtractive process.
- ・ 高抗張力，於薄銅箔易於操作。  
High tensile strength, easy to handle thin foil.
- ・ 最薄之 $7\mu\text{m}$ 銅箔具量產能力。  
From  $7\mu\text{m}$ , we line up.

## 用途/Application

- ・ IC封裝載板  
/Semiconductor Package

## 構成/Composition



## 生產地點/Production Site

- ・ 日本 / Japan

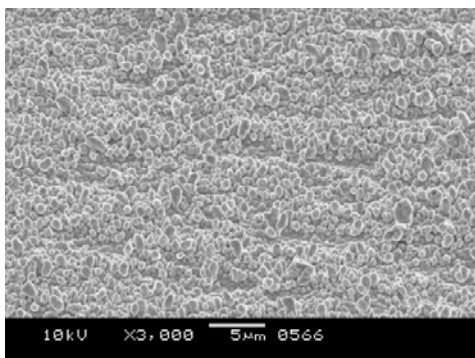
## 代表性特性數據/Representative

	$\mu\text{m}$	Area weight ( $\text{g}/\text{m}^2$ )	Laminate side $R_z(\mu\text{m})$	Tensile Strength ( $\text{N}/\text{mm}^2$ )	Elongation (%)	Peel Strength ( $\text{kg}/\text{cm}$ )@FR-4
3EC-M2S-VLP	9	80	1.8	500	4	0.6
	12	107	1.8	500	5	0.7
	18	153	1.8	500	8	0.8

※上述表列為代表性數據非保證值。

This is representative data, not guaranteed.

處理面/Laminate side



阻劑面/ resist side

